



### 2.0A SBR<sup>®</sup> SURFACE MOUNT SUPER BARRIER RECTIFIER

## Features

- Ultra Low Forward Voltage Drop
- Patented Super Barrier Rectifier Technology
- Soft, Fast Switching Capability
- 150°C Operating Junction Temperature
- Lead Free Finish, RoHS Compliant (Note 1)
- Green Molding Compound (No Halogen and Antimony)
  (Note 2)

# **Mechanical Data**

- Case: SMA
- Case Material: Molded Plastic, UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish.) Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Polarity Indicator: Cathode Band
- Weight: 0.064 grams (approximate)



Top View



Bottom View

# Ordering Information (Note 3)

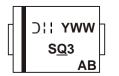
Part Number	Case	Packaging
SBR2U30SA –13	SMA	5000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.

2. Product manufactured with Data Code 0924 (week 24, 2009) and newer are built with Green Molding Compound.

3. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**



SQ3 = Product Type Marking Code DH = Manufacturers' code marking YWW = Date Code Marking Y = Last digit of year (ex: 7 for 2007) WW = Week code (01 to 53) AB = Foundry and Assembly Code



## **Maximum Ratings** $@T_A = 25^{\circ}C$ unless otherwise specified

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Single phase,	nair wave,	60HZ,	resistive	or inductive load.

For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>RM</sub>	30	V
RMS Reverse Voltage	V <sub>R(RMS)</sub>	21	V
Average Rectified Output Current (See Figure 1)	lo	2.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	30	A

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Thermal Resistance Junction to Soldering (Note 4) Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJS</sub> R <sub>θJA</sub>	5 128	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

# **Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	TYP	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	30	-	-	V	I <sub>R</sub> = 400 μA
			0.21	0.26	v	$I_F = 0.1A, T_J = 25^{\circ}C$
			0.11	0.15		I <sub>F</sub> = 0.1A, T <sub>J</sub> = 125°C
Forward Voltage Drop	V <sub>F</sub>		0.31	0.35		$I_F = 1.0A, T_J = 25^{\circ}C$
			0.23	0.30	v	I <sub>F</sub> = 1.0A, T <sub>J</sub> = 125°C
			0.36	0.40		$I_F = 2.0A, T_J = 25^{\circ}C$
			0.30	0.33		$I_F = 2.0A, T_J = 125^{\circ}C$
Leakage Current (Note 6)			210	500	μΑ	V <sub>R</sub> = 30V, T <sub>J</sub> = 25 °C
	I <sub>R</sub>		23	100	mA	V <sub>R</sub> = 30V, T <sub>J</sub> = 125 °C

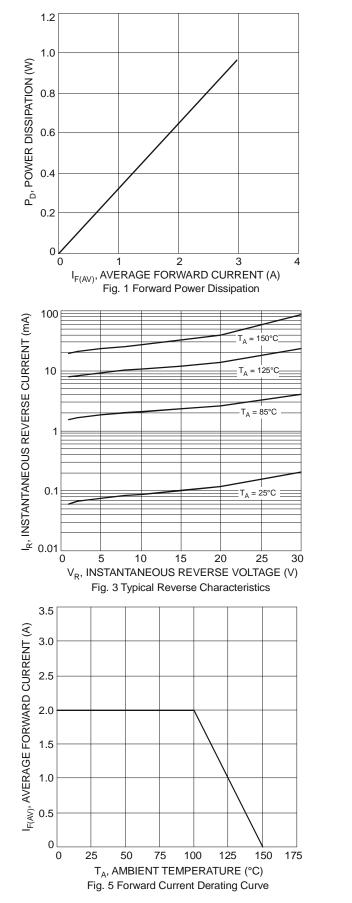
Notes: 4. Theoretical  $R_{eJS}$  calculated from the top center of the die straight down to the PCB cathode tab solder junction.

5. FR-4 PCB, 2 oz. Copper, minimum recommended pad layout per http://www.diodes.com. T<sub>A</sub> = 25°C

6. Short duration pulse test used to minimize self-heating effect.



# SBR2U30SA



SBR is a registered trademark of Diodes Incorporated. SBR2U30SA Document number: DS30997 Rev. 8 - 2



 $\mathsf{T}_{\mathsf{A}},$  AMBIENT TEMPERATURE (°C)

0

0

5

10,000

1,000

100

10

1

10,000

1,000

C<sub>T</sub>, TOTAL CAPACITANCE (pF)

0

= 150°0

0.2

= 85°C

25°C

0.4

V<sub>F</sub>, INSTANTANEOUS FORWARD VOLTAGE (V) Fig. 2 Typical Forward Characteristics

0.6

0.8

 $= -55^{\circ}$ 

 $T_A = 125^{\circ}C$ 

I<sub>F</sub>, INSTANTANEOUS FORWARD CURRENT (mA)

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30

> V<sub>R</sub>, DC REVERSE VOLTAGE (V) Fig. 6 Operating Temperature Derating

15

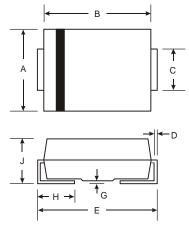
20

25

10

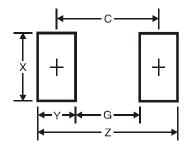


# Package Outline Dimensions



SMA				
Dim	Min	Max		
Α	2.29	2.92		
в	4.00	4.60		
С	1.27	1.63		
D	0.15	0.31		
Е	4.80	5.59		
G	0.05	0.20		
H	0.76	1.52		
J	2.01	2.30		
All Dimensions in mm				

# Suggested Pad Layout



Dimensions	Value (in mm)
Z	6.5
G	1.5
Х	1.7
Y	2.5
С	4.0



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